# **Small Signal MOSFET**

30 V, 250 mA, Dual N-Channel, SC-88

#### **Features**

- Low Gate Charge for Fast Switching
- Small Footprint 30% Smaller than TSOP-6
- ESD Protected Gate
- Pb–Free Package for Green Manufacturing (G Suffix)

#### **Applications**

- Low Side Load Switch
- Li–Ion Battery Supplied Devices Cell Phones, PDAs, DSC
- Buck Converters
- Level Shifts

#### **MAXIMUM RATINGS** (T<sub>.1</sub> = 25°C unless otherwise stated)

Parameter			Symbol	Value	Units
Drain-to-Source Voltage			V <sub>DSS</sub>	30	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain Steady		T <sub>A</sub> = 25 °C	I <sub>D</sub>	250	mA
Current (Note 1)	State	T <sub>A</sub> = 85 °C		180	
Power Dissipation (Note 1)			P <sub>D</sub>	272	mW
Pulsed Drain Current t =10 μs			I <sub>DM</sub>	600	mA
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Source Current (Body Diode)			Is	250	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

1. Surface mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).

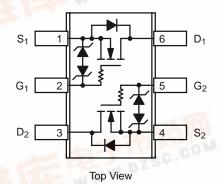


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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> Max		
30 V	1.0 Ω @ 4.0 V	250 mA		
	1.5 Ω @ 2.5 V	250 IIIA		

#### SOT-363 SC-88 (6 LEADS)

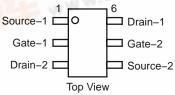




STYLE 26

# MARKING DIAGRAM TED O TE = Device Code D = Date Code

#### **PIN ASSIGNMENT**



#### **ORDERING INFORMATION**

Device	Package	Shipping
NTJD4001NT1	SC-88	3000 Units/Reel
NTJD4001NT1G	SC-88 (Pb-Free)	3000 Units/Reel

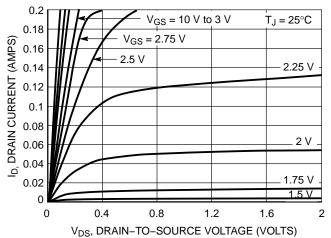


# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise stated)

Parameter	Symbol	Test Con	dition	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V, } I_D = 100 \mu\text{A}$		30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				56		mV/ °C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V	<sub>DS</sub> = 30 V			1.0	μА
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$				±1.0	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{DS}$	ο = 100 μΑ	0.8	1.2	1.5	V
Gate Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-3.2		mV/ °C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = 4.0 \text{ V}, \text{ I}$	<sub>D</sub> = 10 mA		1.0	1.5	Ω
		$V_{GS} = 2.5 \text{ V}, I_D = 10 \text{ mA}$			1.5	2.5	7
Forward Transconductance	9 <sub>FS</sub>	$V_{DS} = 3.0 \text{ V}, I_{D} = 10 \text{ mA}$			80		mS
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>	$V_{GS} = 0 \text{ V, } f = 1.0 \text{ MHz,}$ $V_{DS} = 5.0 \text{ V}$			20	33	pF
Output Capacitance	Coss				19	32	
Reverse Transfer Capacitance	C <sub>RSS</sub>				7.25	12	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = 5.0 \text{ V, V}$ $I_{D} = 0.$	<sub>DS</sub> = 24 V,		0.9	1.3	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	I <sub>D</sub> = 0.1 A			0.2		
Gate-to-Source Charge	Q <sub>GS</sub>				0.3		
Gate-to-Drain Charge	$Q_{GD}$				0.2		
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	td <sub>(ON)</sub>	$V_{GS}$ = 4.5 V, $V_{DD}$ = 5.0 V, $I_{D}$ = 10 mA, $R_{G}$ = 50 $\Omega$			17		ns
Rise Time	tr				23		
Turn-Off Delay Time	td <sub>(OFF)</sub>				94		
Fall Time	tf				82		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		0.65	0.7	V
		$I_S = 10 \text{ mA}$	T <sub>J</sub> = 125°C		0.45		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, dI}_{S}/\text{dt} = 8.0 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ mA}$			12.4		ns

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

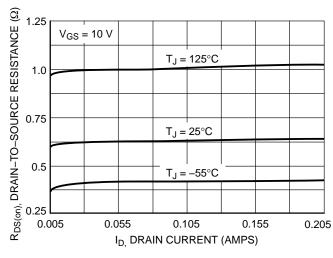
# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



0.1 V<sub>DS</sub> = 5 V 0.08 V<sub>DS</sub> = 5 V T<sub>J</sub> = 125°C 1.2 1.4 1.6 1.8 2 2.2 V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



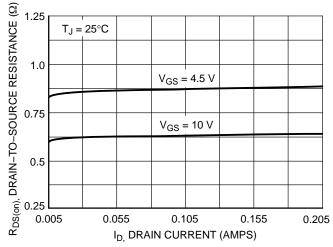
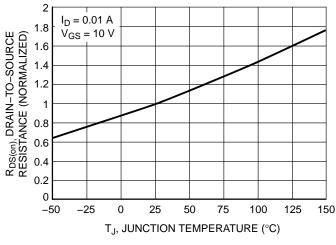
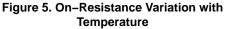


Figure 3. On–Resistance vs. Drain Current and Temperature

Figure 4. On–Resistance vs. Drain Current and Gate Voltage





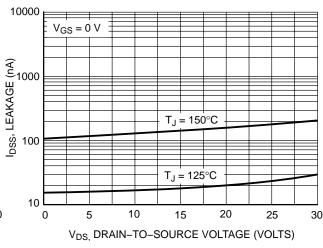
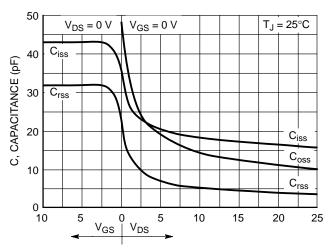
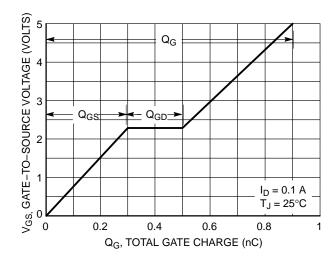


Figure 6. Drain-to-Source Leakage Current vs. Voltage

# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)





GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

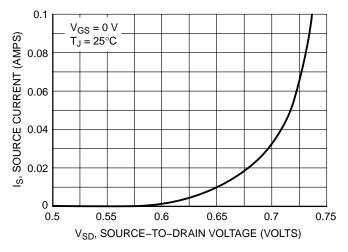
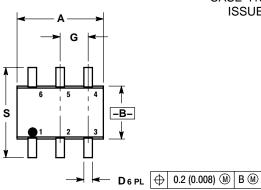
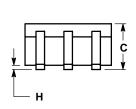


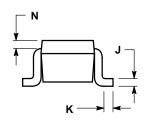
Figure 9. Diode Forward Voltage vs. Current

#### **PACKAGE DIMENSIONS**









- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20 REF		
S	0.079	0.087	2.00	2.20	

- STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1

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